

In the Claims

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

Please amend claim 23 as follows:

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23. (Twice Amended) A process for the adhesive-free production of polymeric components, including the steps of:
- (a) preparing a polymeric substrate which, on at least one surface, has depressions forming micro- and/or nanochannel structures,
 - (b) applying, by uniform pressure in the range of from 0.1 to 1000 kg/cm² extending over said surface, a polymeric covering to said surface,
 - (c) slowly heating said substrate, with said covering applied by pressure, to a temperature which is at least as high as the glass transition temperature of said substrate and/or of said covering and holding the substrate with the covering at such temperature for at least 15 minutes, for the bonding thereof, and
 - (d) cooling.

REMARKS

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "**Version with markings to show changes made.**"

This amendment is responsive to the Office Action mailed July 2, 2002, please consider the following remarks.